

# Catalytic Effect of Substrate-Si on SiO<sub>2</sub>-IL Scavenging in HfO<sub>2</sub>/SiO<sub>2</sub>/Si Stacks

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SiO<sub>2</sub> interface layer (IL) scavenging in HfO<sub>2</sub>/SiO<sub>2</sub>/Si stacks has been discussed by focusing on oxygen vacancy (V<sub>O</sub>) transfer at HfO<sub>2</sub>/SiO<sub>2</sub> interface [1]. In our previous work, however, the substrate-Si was found to be significant for scavenging as well [2, 3]. This work discusses what really occurs at SiO<sub>2</sub>/substrate interface in SiO<sub>2</sub>-IL scavenging of HfO<sub>2</sub> gate stacks.

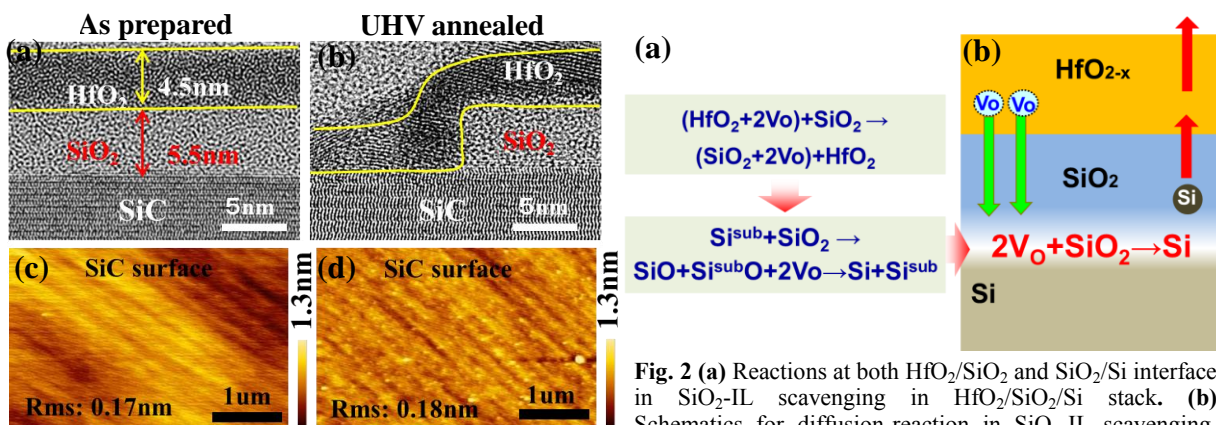
The SiO<sub>2</sub> scavenging in HfO<sub>2</sub> gate stack was achieved by ultra-high vacuum (UHV) annealing [4]. We found that no SiO<sub>2</sub> scavenging on sapphire substrate but a clear one on SiC. It indicates substrate-“Si” is necessary for scavenging [2, 3]. Three possibilities for the substrate effect: 1) substrate-Si attracts Si growth from scavenged SiO<sub>2</sub>, 2) substrate-Si is consumed, and 3) substrate-Si plays a catalytic effect on scavenging. To differentiate among three cases, samples with inhomogeneous SiO<sub>2</sub>-IL scavenging were analyzed by the TEM, AFM and XPS. Inhomogeneous SiO<sub>2</sub>-IL scavenging appears on SiC substrate with relatively thick SiO<sub>2</sub> and HfO<sub>2</sub>. TEM images in **Fig. 1(a)** and **(b)** show that SiC surface keeps flat in both regions w/ and w/o SiO<sub>2</sub> scavenging. There is no Si appearance on SiC surface even in the scavenging region confirmed by EELS. After removing HfO<sub>2</sub> and SiO<sub>2</sub> by HF, SiC surface (**Fig. 1(d)**) is as smooth as that of as-prepared sample (**Fig. 1(c)**). Note that no Si was detected on SiC surface by XPS as well. These results indicate no Si growth, no substrate Si consumption in scavenging. Thus the substrate-Si should have a catalytic effect on scavenging reaction.

It is worth noting that SiO is prone to be formed at the SiO<sub>2</sub>/Si and SiO<sub>2</sub>/SiC interfaces [6]. It is possible that Si play a catalytic effect on scavenging through SiO as an intermediate product as shown in **Fig. 2(a)**. Thus the net reaction of scavenging should occur at SiO<sub>2</sub>/Si interface. Based on this view as well as V<sub>O</sub> kinetics and Si up-diffusion clarified previously [3, 6], a kinetic model for SiO<sub>2</sub>-IL scavenging in HfO<sub>2</sub>/SiO<sub>2</sub>/Si stack is proposed as schematically show in **Fig. 2(b)**.

In summary, neither Si growth nor substrate consumption in SiO<sub>2</sub>-IL scavenging of HfO<sub>2</sub>/SiO<sub>2</sub>/Si stack has been demonstrated. SiO<sub>2</sub>/Si interface reaction with a catalytic effect of substrate-Si couples the in-diffusion of V<sub>O</sub> from HfO<sub>2</sub> with the out-diffusion of Si through SiO<sub>2</sub> and HfO<sub>2</sub> layers. This is the key to understanding of the SiO<sub>2</sub>-IL scavenging.

**Acknowledgements:** This work was partly in collaboration with STARC. Xiuyan Li was grateful to the Marubun Research Promotion Foundation and China Scholarship Council for financial support.

**References:** [1] T. Ando, *Materials*, **5** (2012) 478. [2] X. Li *et al.*, IWDTF, 2013, S2-4. [3] X. Li *et al.*, SSDM, 2014.,F3-3. [4] X. Li *et al.*, *Thin Solid Films*, **557** (2014) 272 [5] X. Li *et al.*, *Appl. Phys. Lett.*, **105**, (2014) 182902. [6] X. Li *et al.*, JSAP, 2014 (autumn), 19a-A17-1.



**Fig. 1** TEM /AFM (SiC surface after removing HfO<sub>2</sub> and SiO<sub>2</sub> layer by HF solution) images of HfO<sub>2</sub>/SiO<sub>2</sub>/SiC stacks **(a)/(c)** prepared and **(b)/(d)**annealed in UHV at 1000°C for 30min.